

## HiPerFRED

$V_{RRM}$  = 600V  
 $I_{FAV}$  = 2x 10A  
 $t_r$  = 30ns

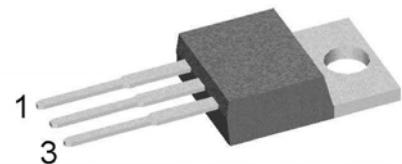
High Performance Fast Recovery Diode

Low Loss and Soft Recovery

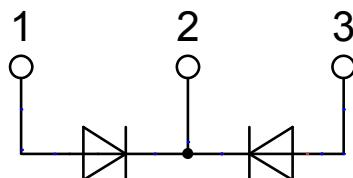
Common Cathode

Part number

DSEC16-06A



Backside: cathode



### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low  $I_{rm}$ -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low  $I_{rm}$  reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

### Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

### Package: TO-220

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

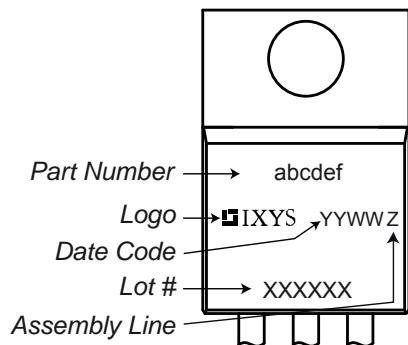
## Fast Diode

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			600	V
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			600	V
$I_R$	reverse current, drain current	$V_R = 600 V$ $V_R = 600 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		60 0.25	$\mu A$ mA
$V_F$	forward voltage drop	$I_F = 10 A$ $I_F = 20 A$ $I_F = 10 A$ $I_F = 20 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		2.10 2.32 1.42 1.68	V V
$I_{FAV}$	average forward current	$T_C = 135^\circ C$ rectangular $d = 0.5$	$T_{VJ} = 175^\circ C$		10	A
$V_{F0}$ $r_F$	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ C$		1.03 25.1	V $m\Omega$
$R_{thJC}$	thermal resistance junction to case				2.5	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.50		K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ C$		60	W
$I_{FSM}$	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}; V_R = 0 V$	$T_{VJ} = 45^\circ C$		50	A
$C_J$	junction capacitance	$V_R = 400 V$ $f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$		6	pF
$I_{RM}$	max. reverse recovery current		$T_{VJ} = 25^\circ C$ $T_{VJ} = 100^\circ C$		4 6	A A
$t_{rr}$	reverse recovery time	$I_F = 10 A; V_R = 100 V$ $-di_F/dt = 200 A/\mu s$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 100^\circ C$		30 90	ns ns

**Package TO-220**

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$I_{RMS}$	$RMS$ current	per terminal <sup>1)</sup>			35	A
$T_{stg}$	storage temperature		-55		150	°C
$T_{VJ}$	virtual junction temperature		-55		175	°C
<b>Weight</b>				2		g
$M_D$	mounting torque		0.4		0.6	Nm
$F_c$	mounting force with clip		20		60	N

<sup>1)</sup>  $I_{RMS}$  is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a common cathode/anode configuration with a non-isolated backside, the current capability can be increased by connecting the backside.

**Product Marking**

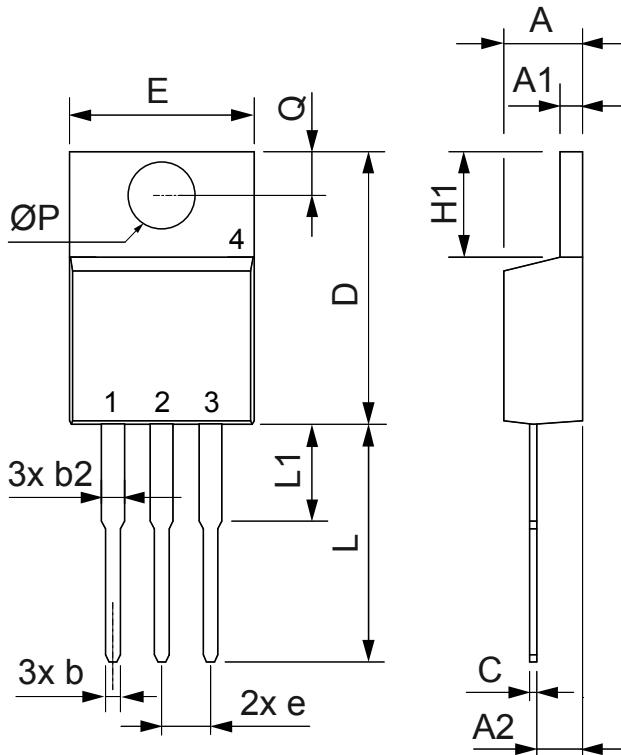
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEC16-06A	DSEC16-06A	Tube	50	475130

Similar Part	Package	Voltage class
DSEC16-06AC	ISOPLUS220AB (3)	600

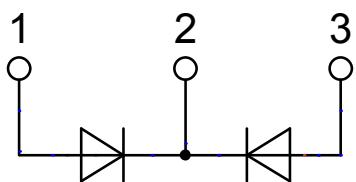
**Equivalent Circuits for Simulation***\* on die level* $T_{VJ} = 175^\circ\text{C}$ 

$I$	$V_0$	$R_0$	Fast Diode	
$V_{0\max}$	threshold voltage	1.03		V
$R_{0\max}$	slope resistance *	22		$\text{m}\Omega$

## Outlines TO-220



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.32	4.82	0.170	0.190
A1	1.14	1.39	0.045	0.055
A2	2.29	2.79	0.090	0.110
b	0.64	1.01	0.025	0.040
b2	1.15	1.65	0.045	0.065
C	0.35	0.56	0.014	0.022
D	14.73	16.00	0.580	0.630
E	9.91	10.66	0.390	0.420
e	2.54	BSC	0.100	BSC
H1	5.85	6.85	0.230	0.270
L	12.70	13.97	0.500	0.550
L1	2.79	5.84	0.110	0.230
ØP	3.54	4.08	0.139	0.161
Q	2.54	3.18	0.100	0.125



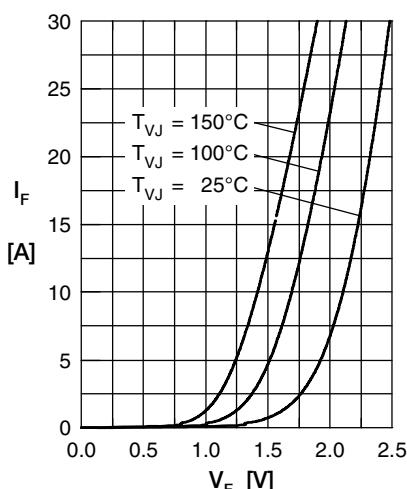
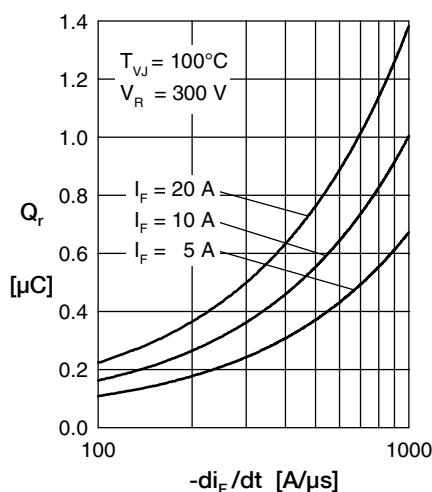
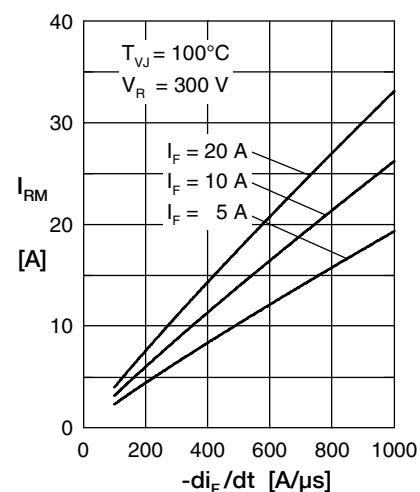
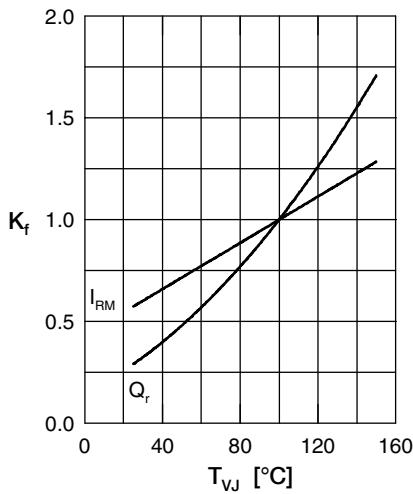
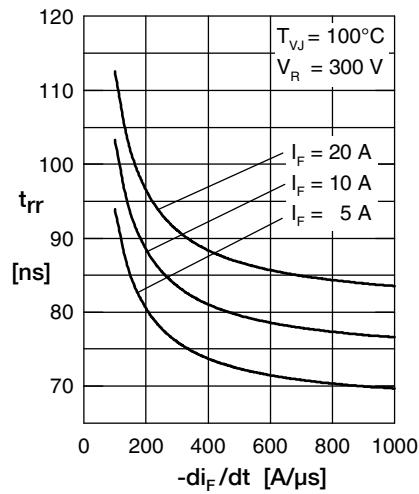
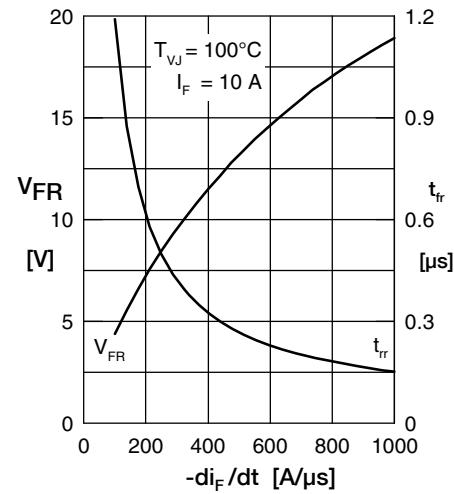
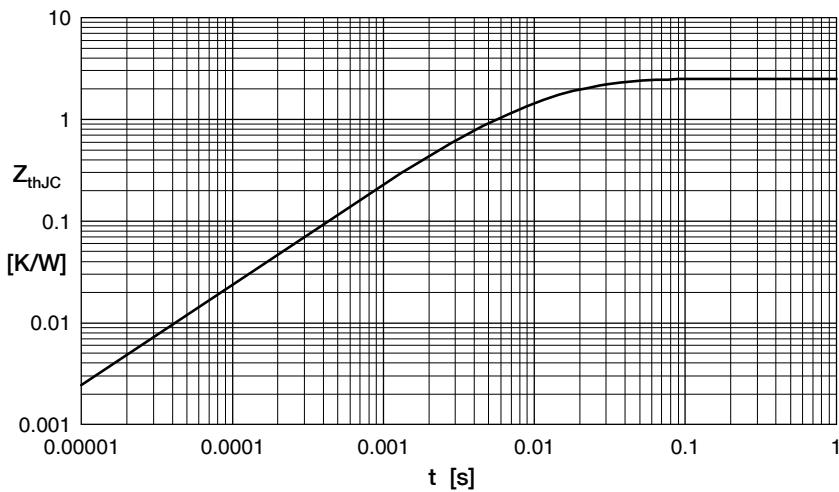
**Fast Diode**Fig. 1 Forward current  $I_F$  versus  $V_F$ Fig. 2 Typ. reverse recov. charge  $Q_r$  versus  $-di_F/dt$ Fig. 3 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$ Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$ Fig. 5 Typ. recovery time  $t_{rr}$  versus  $-di_F/dt$ Fig. 6 Typ. peak forward voltage  $V_{FR}$  and  $t_{fr}$  versus  $di_F/dt$ 

Fig. 7 Transient thermal impedance junction to case

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ [K/W]	$t_i$ [s]
1	1.449	0.0052
2	0.5578	0.0003
3	0.4931	0.0169